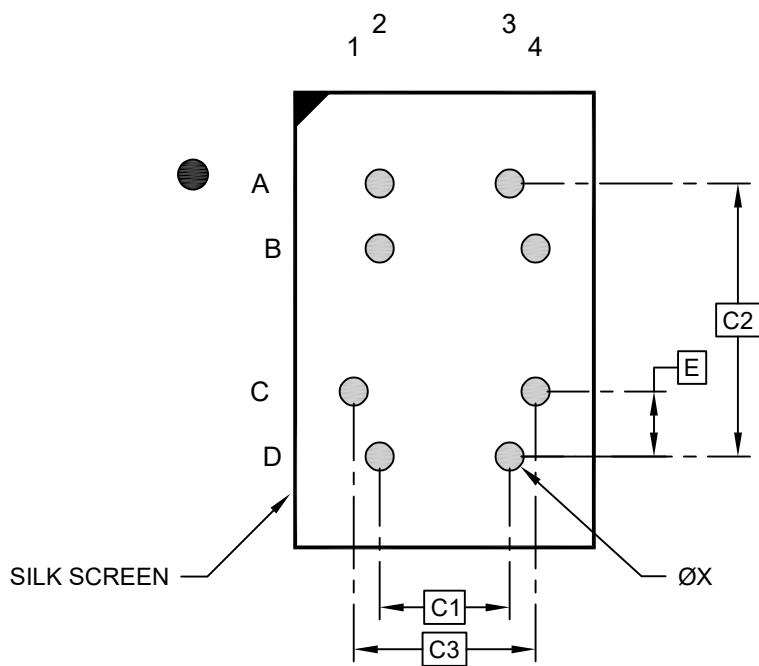


8-Ball Wafer Level Chip Scale Package (FEB) - [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1	1.00 BSC		
Contact Pad Spacing	C3	1.40 BSC		
Contact Pad Spacing	C2	2.10 BSC		
Contact Pad Width (Xnn)	X1	0.22		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.